



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT DESCRIPTION

Laird's Tflex™ HD90000 is the latest product in our High Deflection series. Tflex™ HD90000 combines 7.5 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

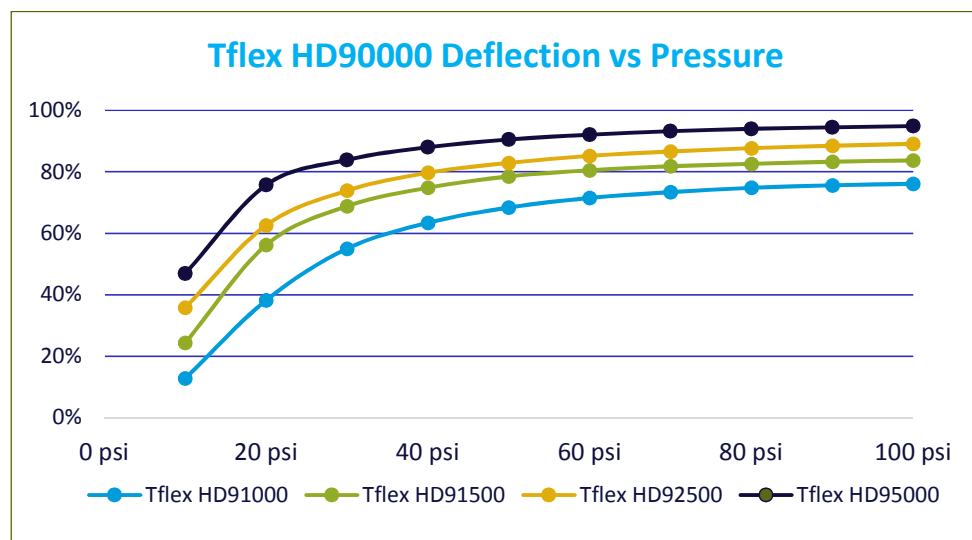
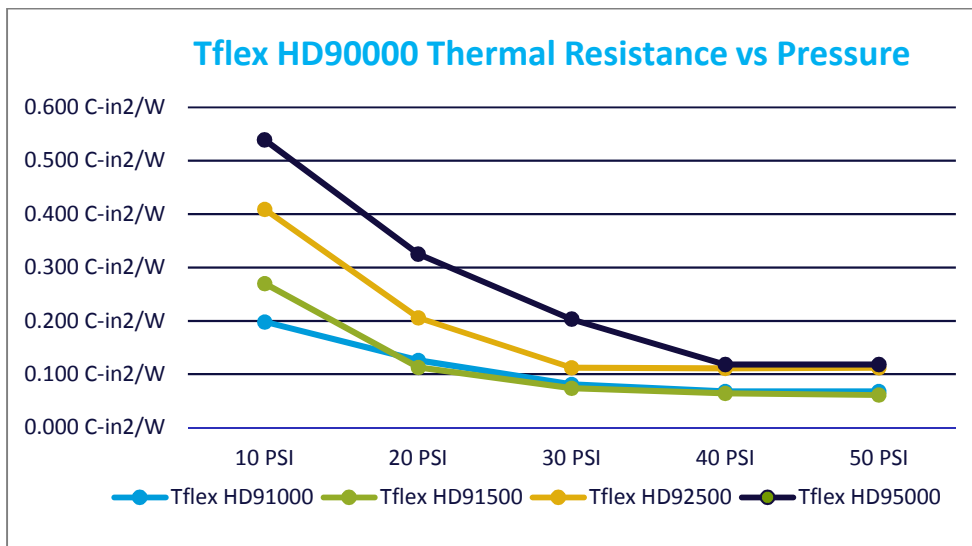
Tflex™ HD90000 is available in thickness from 0.040" (1000 µm) to 0.200" (5000 µm). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

- 7.5 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress
- Low Outgassing
- Low D3-D20 (< 20ppm)
- Large tolerance applications
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	0.040" (1000 µm) - 0.20" (5000 µm)	N/A
Thermal Conductivity (W/mK)	7.5	Hot Disk
Density (g/cc)	3.5	Helium Pycnometer
Hardness (Shore 00)	22	ASTM D2240
Outgassing TML (weight %)	0.17	ASTM E595
Outgassing CVCM (weight %)	0.01	ASTM E595
Temperature Range	-50°C to 125°C	Laird Test Method
Rth at 40 mils, 10 psi, 50° C	0.198°C-in ² /W	ASTM D5470
Dielectric Constant at 1 MHz	8.14	ASTM D150
UL Flammability Rating	V-0 pending	UL 94
Volume Resistivity	8.73×10 ¹³ ohm-cm	ASTM D257



AVAILABILITY

STANDARD THICKNESSES

- 0.040" (1000 µm) up to 0.200" (5000 µm) thick material available in 250 µm increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts.

OPTIONS

- DC1 – eliminate tack from one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD90000 indicates Tflex™ HD90000 product line with thickness in microns

EXAMPLES:

- Tflex™ HD91000= 1000 µm (0.040") thick Tflex™ HD90000 material
- Tflex™ HD95000= 5000 µm (0.200") thick Tflex™ HD90000 material

A17807-00 Tflex™ HD90000 DS 092017